



Nordson Test & Inspection to Unveil Revolutionary SonoFlex Acoustic Inspection System at SEMICON West 2026

MINNEAPOLIS, Minn. – September 2026 – [Nordson Test & Inspection](#), a global leader in inspection, metrology, and testing solutions, will showcase its comprehensive portfolio of industry-leading optical, X-ray, acoustic inspection, and metrology technologies powered by the Nordson Intelligence™ Ecosystem at **SEMICON West 2026**, October 13–15, in Booth 5844 at the Moscone Center in San Francisco, California.

Highlighting the exhibition will be the worldwide debut of the new [SonoFlex™](#) Acoustic Microscopy Inspection (AMI) System, an innovative platform designed to redefine acoustic inspection performance for back-end advanced semiconductor manufacturing.

Combining breakthrough ThruScan imaging technology with intelligent AI-powered analytics, SonoFlex delivers exceptional image quality, highly accurate defect detection, and significantly increased throughput for small-panel applications. The system incorporates advanced pulser and transducer technologies that enable scanning speeds up to twice as fast as conventional solutions while maintaining high-resolution imaging performance.



Its modular architecture simplifies maintenance and serviceability while enabling scalable multi-system configurations capable of increasing throughput by up to eight times. Powered by [FlexCore™](#) software and Nordson's N-Intelligence [Multi-Gate Image Analysis](#) (MGIA) technology, SonoFlex automatically identifies defects, isolates true void counts, and supports complex device and process analysis. The result is improved product quality, greater manufacturing efficiency, and deeper process insight through advanced acoustic inspection and imaging capabilities.

In addition to SonoFlex, Nordson will showcase a broad range of advanced inspection and metrology solutions designed to enhance yield, process control, and productivity across front-end, mid-end, and back-end semiconductor manufacturing operations.

Semiconductor Back-End Solutions Demonstrated

The [SQ7000+™](#) delivers high-speed, high-accuracy inspection and metrology with an ultra-high-resolution Multi-Reflection Suppression (MRS®) sensor technology, which effectively eliminates reflections from shiny and highly specular surfaces. Combined with an advanced coordinate measurement software suite, and AI-

powered capabilities, the platform is ideally suited for advanced packaging and other applications requiring the highest levels of precision and quality assurance.

Designed specifically for microelectronics applications, including wire bond inspection, the [SQ3000 M2](#) provides exceptional accuracy and resolution. Leveraging Focus Variation Metrology (FVM) technology and high-resolution telecentric optics, the system delivers industry-leading defect coverage and comprehensive metrology capabilities for increasingly complex semiconductor devices.

Nordson will also feature [Dynamic Planar CT](#), the next generation of 3D Planar X-ray technology for Nordson's automated X-ray inspection (AXI) systems. Utilizing a new reconstruction algorithm, Dynamic Planar CT delivers superior image quality, enhanced layer separation, and exceptional defect visibility. The technology provides a larger field of view and up to twice the image acquisition speed of conventional Planar CT solutions, improving throughput while reducing radiation exposure. It is particularly effective for semiconductor applications such as flip-chip and micro-bump inspection.

The [Quadra® 7 Pro](#) establishes a new benchmark for 2D and 3D manual X-ray inspection in semiconductor back-end manufacturing. Equipped with Nordson's industry-leading Onyx® detector and Dual Mode Quadra NT4® X-ray tube, the system enables seamless switching between brightness and high-resolution imaging modes, providing operators with unmatched flexibility and image clarity across a wide range of inspection applications.

Powered by industry-proven C-SAM® technology, the [Gen7™](#) AMI system provides fast, highly accurate detection of delamination, voids, cracks, and other internal defects. The platform is ideally suited for laboratory analysis, failure investigation, and high-resolution applications requiring the most advanced acoustic microscopy performance.

Semiconductor Mid-End Solutions Featured

The [SpinSAM™](#) AMI system sets a new benchmark in the industry with its high throughput and superior sensitivity, enabling precise defect detection for Wafer-Level and Advanced Packaging applications including bonded wafers, Chip-on-Wafer, stacked wafers, MEMS, and over-molded wafers. Using an innovative spin-scanning method, the system scans up to four 300mm wafers simultaneously, achieving an impressive speed of 41 wafers per hour. This breakthrough scanning capability, combined with superior defect capture and image quality, enhances both productivity and accuracy in semiconductor inspection.

The [XM8000Pro](#) redefines high-performance 3D X-ray metrology for advanced semiconductor manufacturing. Built specifically to handle demanding advanced Wafer-Level and Panel-Level Packaging, the delivers sub-micron 3D reconstruction with unprecedented imaging fidelity and production-speed throughput.

The Bond Test [4800 Integra Plus](#) system is the next generation automated bond test solution designed to meet the dynamic Wafer-Level Packaging environment.

Semiconductor Front-End Solutions Demonstrated

Nordson will also demonstrate its [WaferSense® AGS2](#) and [ACS](#) wireless metrology sensors designed for capturing and analyzing real-time data for effective semiconductor tool set-up and maintenance. The ACS “sees” inside equipment to capture dimensional offset data (x,y and z) to quickly center wafer transfer positions. The AGS2 speeds non-contact gap measurements and parallelism adjustments under vacuum, improving uniformity, tool availability and repeatability in a thinner and lighter form-factor.

AI Across Semiconductor Landscape

As part of its expanding [Nordson Intelligence™](#) Ecosystem, Nordson continues to advance the application of machine learning, deep learning, and artificial intelligence across inspection and metrology platforms. Visitors will experience how these intelligent technologies are helping manufacturers accelerate process optimization, improve defect classification, and drive higher production yields.

Visit Nordson Test & Inspection in Booth 5844 to experience live demonstrations and discover how Nordson’s innovative inspection, metrology, and test solutions are helping semiconductor manufacturers improve yields, optimize processes, and increase productivity across the industry.

About Nordson Test & Inspection

Nordson Test & Inspection is uniquely positioned with an industry-leading portfolio of proprietary test, inspection and metrology solutions including Acoustic, Optical, X-ray technologies for Semiconductor and SMT customers to improve yields, processes and productivity. Nordson Test & Inspection is at the forefront, advancing advanced AI, DL, and ML capabilities, all under the Nordson Intelligence ecosystem. Best-in-class high-precision technologies are complemented by passionate sales and support teams, unmatched consultative applications expertise and a strong focus on operational excellence with a broad global reach.

About Nordson

Nordson Corporation (Nasdaq: NDSN) is an innovative precision technology company that leverages a scalable growth framework through an entrepreneurial, division-led organization to deliver top tier growth with leading margins and returns. The Company’s direct sales model and applications expertise serves global customers through a wide variety of critical applications. Its diverse end market exposure includes consumer non-durable, medical, electronics and industrial end markets. Founded in 1954 and headquartered in Westlake, Ohio, the Company has operations and support offices in over 35 countries. Visit Nordson at www.Nordson.Com or [linkedin/Nordson](#).